DATA SHEET

NE/SA/SE555/SE555C
Timer

Product data
Supersedes data of 1994 Aug 31

2003 Feb 14

Philips
Semiconductors

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DESCRIPTION

The 555 monolithic timing circuit is a highly stable controller capable of producing accurate time delays, or oscillation. In the time delay mode of operation, the time is precisely controlled by one external resistor and capacitor. For a stable operation as an oscillator, the free running frequency and the duty cycle are both accurately controlled with two external resistors and one capacitor. The circuit may be triggered and reset on falling waveforms, and the output structure can source or sink up to 200 mA.

FEATURES

- Turn-off time less than 2 µs
- Max. operating frequency greater than 500 kHz
- Timing from microseconds to hours
- Operates in both astable and monostable modes
- High output current
- Adjustable duty cycle
- TTL compatible
- Temperature stability of 0.005% per °C

APPLICATIONS

- Precision timing
- Pulse generation
- Sequential timing
- Time delay generation
- Pulse width modulation

PIN CONFIGURATION

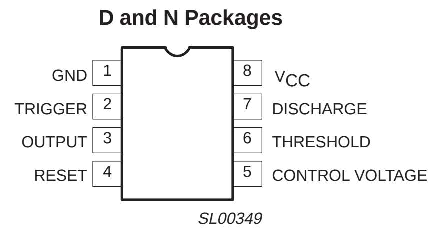


Figure 1. Pin configuration

BLOCK DIAGRAM

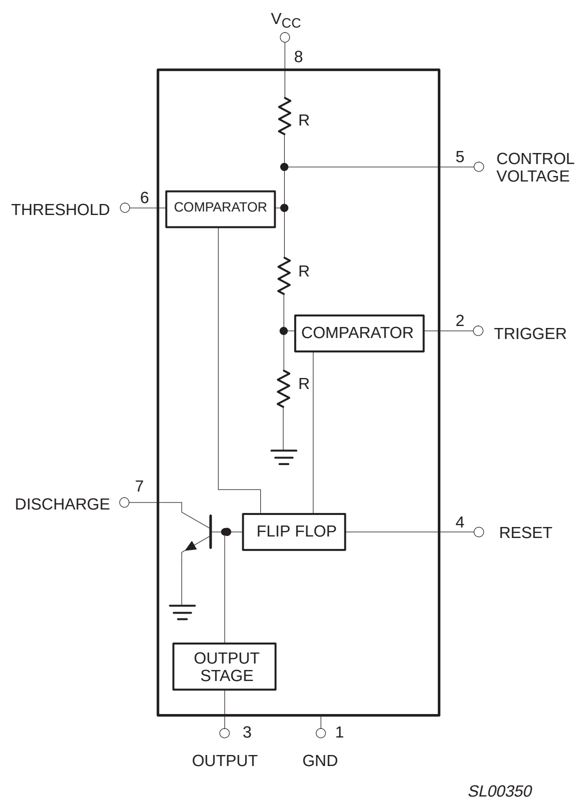


Figure 2. Block Diagram

ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
8-Pin Plastic Small Outline (SO) Package	0 to +70 °C	NE555D	SOT96-1
8-Pin Plastic Dual In-Line Package (DIP)	0 to +70 °C	NE555N	SOT97-1
8-Pin Plastic Small Outline (SO) Package	–40 °C to +85 °C	SA555D	SOT96-1
8-Pin Plastic Dual In-Line Package (DIP)	–40 °C to +85 °C	SA555N	SOT97-1
8-Pin Plastic Dual In-Line Package (DIP)	–55 °C to +125 °C	SE555CN	SOT97-1
8-Pin Plastic Dual In-Line Package (DIP)	–55 °C to +125 °C	SE555N	SOT97-1

EQUIVALENT SCHEMATIC

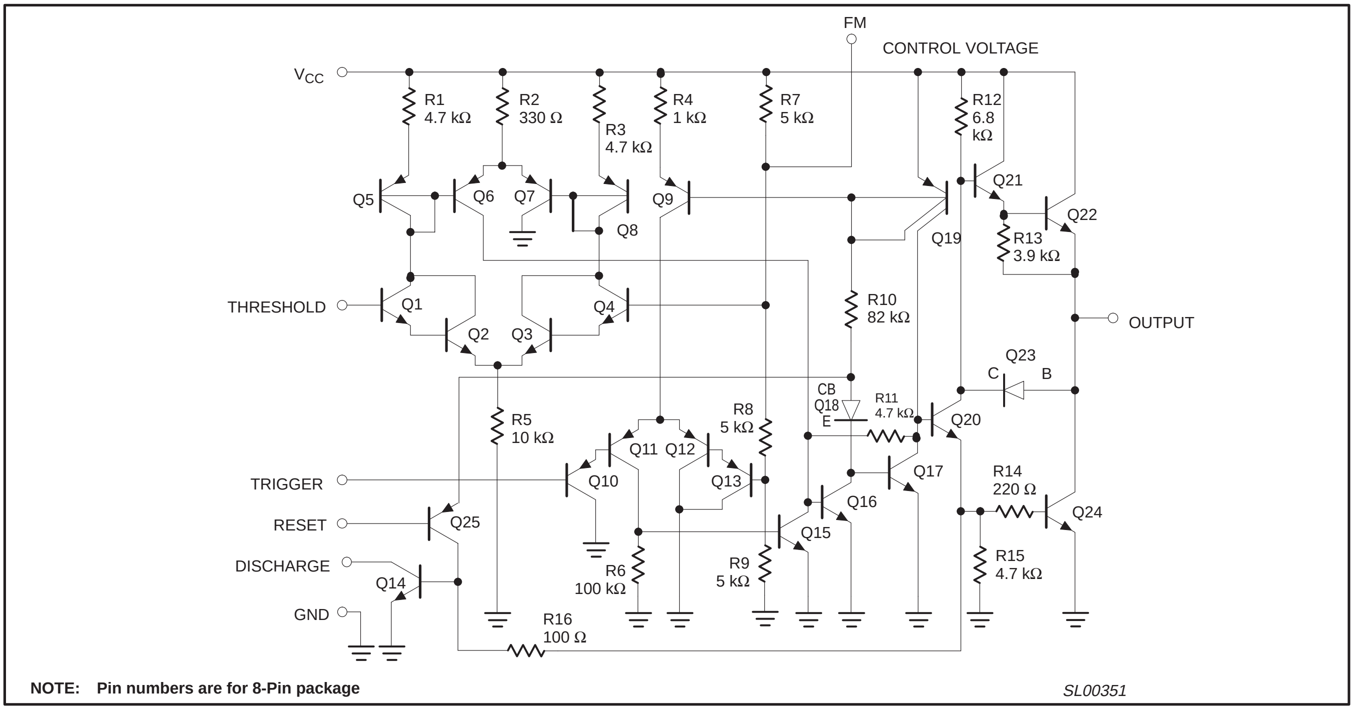


Figure 3. Equivalent schematic

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage SE555 NE555, SE555C, SA555	 +18 +16	 V V
P_D	Maximum allowable power dissipation[1]	600	mW
T_{amb}	Operating ambient temperature range NE555 SA555 SE555, SE555C	 0 to +70 –40 to +85 –55 to +125	 °C °C °C
T_{stg}	Storage temperature range	–65 to +150	°C
T_{SOLD}	Lead soldering temperature (10 sec max)	+230	°C

NOTE:

1. The junction temperature must be kept below 125 °C for the D package and below 150°C for the N package.
   At ambient temperatures above 25 °C, where this limit would be derated by the following factors:
   D package 160 °C/W
   N package 100 °C/W

DC AND AC ELECTRICAL CHARACTERISTICS

T_{amb} = 25 °C, V_{CC} = +5 V to +15 V unless otherwise specified.

SYMBOL	PARAMETER	TEST CONDITIONS	SE555			NE555/SA555/SE555C			UNIT
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	Supply voltage		4.5		18	4.5		16	V
I_{CC}	Supply current (low state)[1]	V_{CC} = 5 V, R_L = ∞ V_{CC} = 15 V, R_L = ∞		3 10	5 12		3 10	6 15	mA mA
 t_M $\Delta t_M/\Delta T$ $\Delta t_M/\Delta V_S$	Timing error (monostable) Initial accuracy[2] Drift with temperature Drift with supply voltage	R_A = 2 kΩ to 100 kΩ C=0.1 μF		 0.5 30 0.05	 2.0 100 0.2		 1.0 50 0.1	 3.0 150 0.5	 % ppm/°C %/V
 t_A $\Delta t_A/\Delta T$ $\Delta t_A/\Delta V_S$	Timing error (astable) Initial accuracy[2] Drift with temperature Drift with supply voltage	R_A, R_B = 1 kΩ to 100 kΩ C = 0.1 μF V_{CC} = 15 V		 4 0.15	 6 500 0.6		 5 0.3	 13 500 1	 % ppm/°C %/V
V_C	Control voltage level	V_{CC} = 15 V V_{CC} = 5 V	9.6 2.9	10.0 3.33	10.4 3.8	9.0 2.6	10.0 3.33	11.0 4.0	V V
V_{TH}	Threshold voltage	V_{CC} = 15 V V_{CC} = 5 V	9.4 2.7	10.0 3.33	10.6 4.0	8.8 2.4	10.0 3.33	11.2 4.2	V V
I_{TH}	Threshold current[3]			0.1	0.25		0.1	0.25	μA
V_{TRIG}	Trigger voltage	V_{CC} = 15 V V_{CC} = 5 V	4.8 1.45	5.0 1.67	5.2 1.9	4.5 1.1	5.0 1.67	5.6 2.2	V V
I_{TRIG}	Trigger current	V_{TRIG} = 0 V		0.5	0.9		0.5	2.0	μA
V_{RESET}	Reset voltage[4]	V_{CC} = 15 V, V_{TH} = 10.5 V	0.3		1.0	0.3		1.0	V
I_{RESET}	Reset current Reset current	V_{RESET} = 0.4 V V_{RESET} = 0 V		0.1 0.4	0.4 1.0		0.1 0.4	0.4 1.5	mA mA
V_{OL}	LOW-level output voltage	V_{CC} = 15 V I_{SINK} = 10 mA I_{SINK} = 50 mA I_{SINK} = 100 mA I_{SINK} = 200 mA		 0.1 0.4 2.0 2.5	 0.15 0.5 2.2		 0.1 0.4 2.0 2.5	 0.25 0.75 2.5	 V V V V
		V_{CC} = 5 V I_{SINK} = 8 mA I_{SINK} = 5 mA		 0.1 0.05	 0.25 0.2		 0.3 0.25	 0.4 0.35	 V V
V_{OH}	HIGH-level output voltage	V_{CC} = 15 V I_{SOURCE} = 200 mA I_{SOURCE} = 100 mA	 13.0	 12.5 13.3		 12.75	 12.5 13.3		 V V
		V_{CC} = 5 V I_{SOURCE} = 100 mA	 3.0	 3.3		 2.75	 3.3		 V
t_{OFF}	Turn-off time[5]	V_{RESET} = V_{CC}		0.5	2.0		0.5	2.0	μs
t_R	Rise time of output			100	200		100	300	ns
t_F	Fall time of output			100	200		100	300	ns
	Discharge leakage current			20	100		20	100	nA

NOTES:

1. Supply current when output high typically 1 mA less.
2. Tested at V_{CC} = 5 V and V_{CC} = 15 V.
3. This will determine the max value of R_A+R_B, for 15 V operation, the max total R = 10 MΩ, and for 5 V operation, the max. total R = 3.4 MΩ.
4. Specified with trigger input HIGH.
5. Time measured from a positive-going input pulse from 0 to 0.8×V_{CC} into the threshold to the drop from HIGH to LOW of the output. Trigger is tied to threshold.

TYPICAL PERFORMANCE CHARACTERISTICS

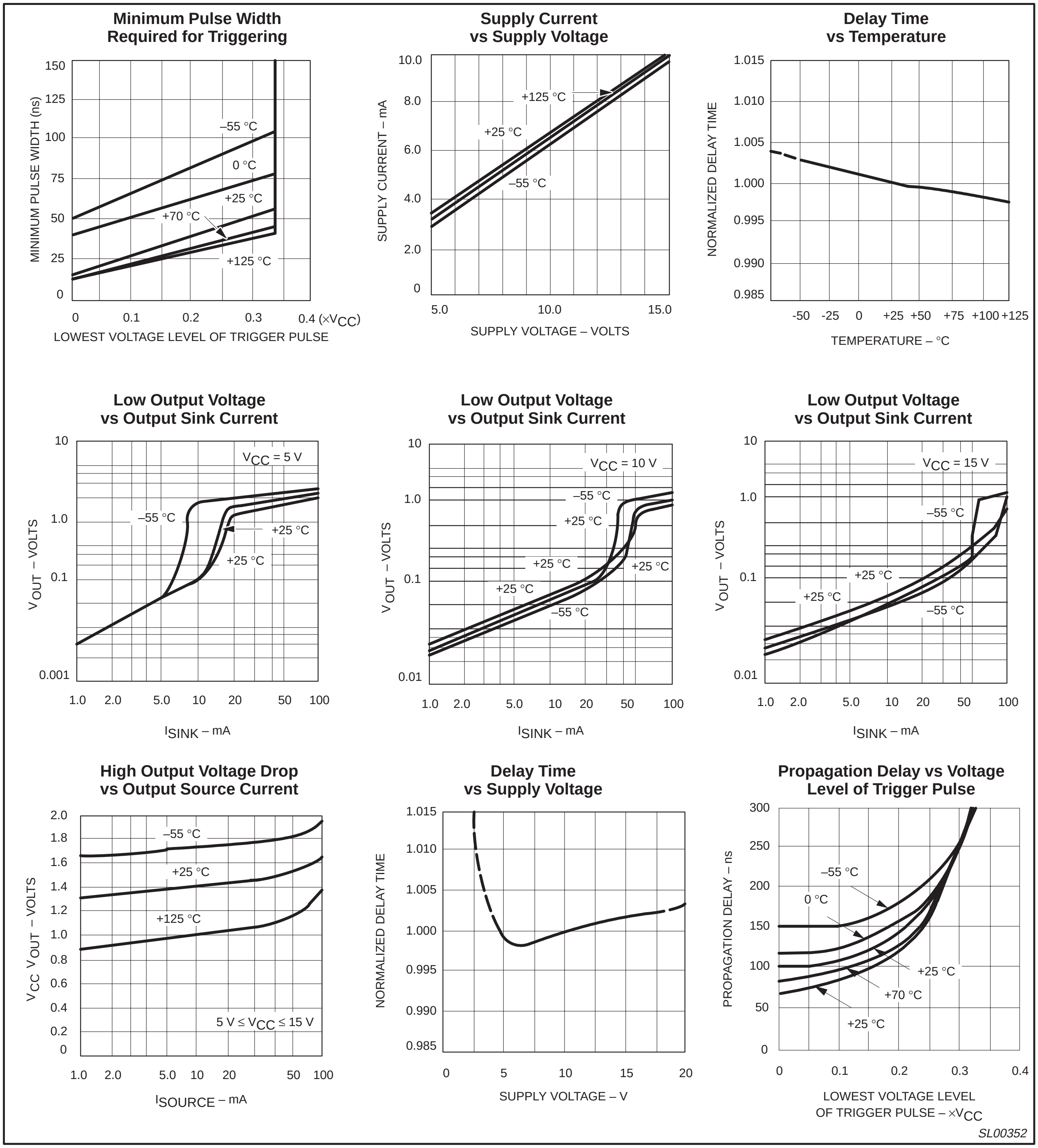


Figure 4. Typical Performance Characteristics

TYPICAL APPLICATIONS

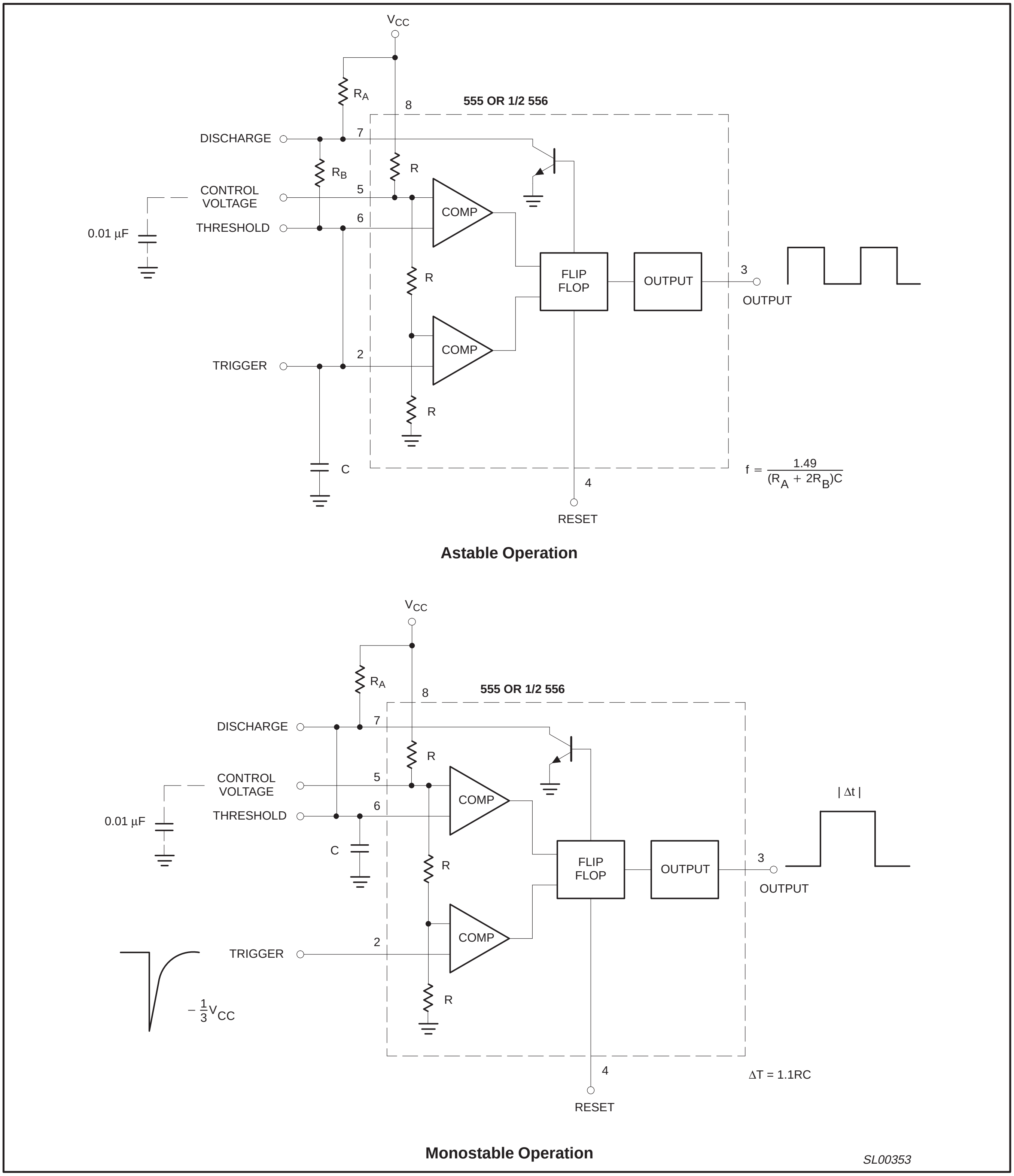


Figure 5. Typical Applications

TYPICAL APPLICATIONS

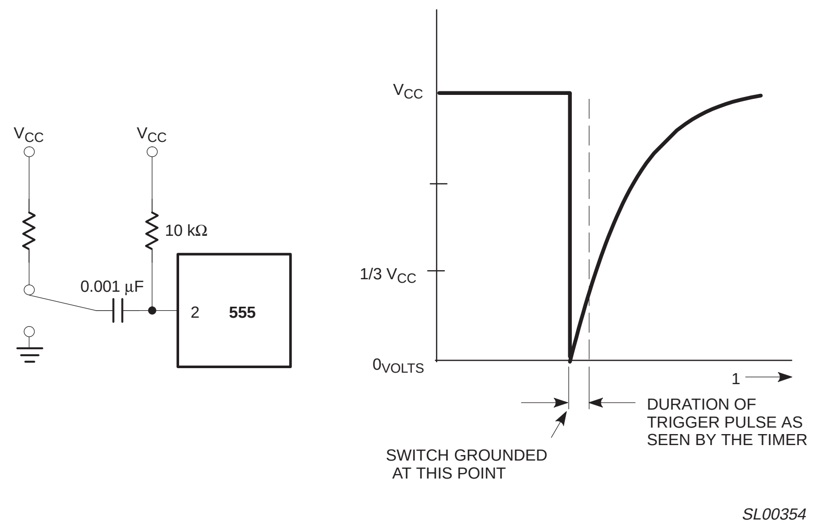


Figure 6. AC Coupling of the Trigger Pulse

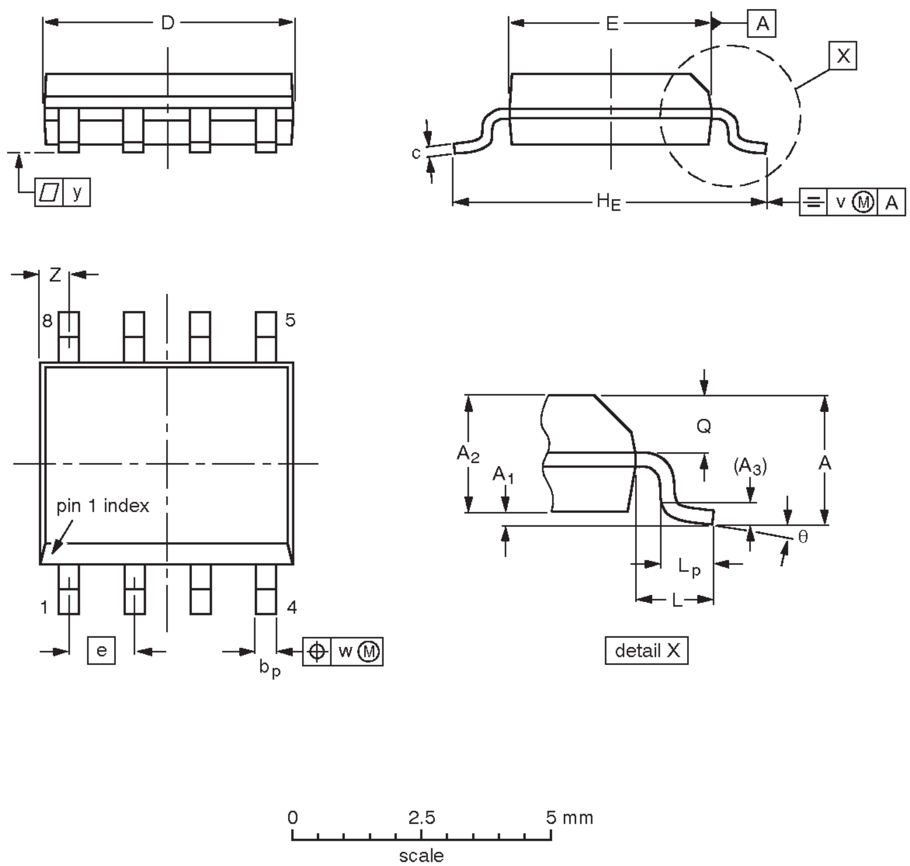
Trigger Pulse Width Requirements and Time Delays

Due to the nature of the trigger circuitry, the timer will trigger on the negative going edge of the input pulse. For the device to time out properly, it is necessary that the trigger voltage level be returned to some voltage greater than one third of the supply before the time out period. This can be achieved by making either the trigger pulse sufficiently short or by AC coupling into the trigger. By AC coupling the trigger, see Figure 6, a short negative going pulse is achieved when the trigger signal goes to ground. AC coupling is most frequently used in conjunction with a switch or a signal that goes to ground which initiates the timing cycle. Should the trigger be held low, without AC coupling, for a longer duration than the timing cycle the output will remain in a high state for the duration of the low trigger signal, without regard to the threshold comparator state. This is due to the predominance of Q_{15} on the base of Q_{16}, controlling the state of the bi-stable flip-flop. When the trigger signal then returns to a high level, the output will fall immediately. Thus, the output signal will follow the trigger signal in this case.

Another consideration is the “turn-off time”. This is the measurement of the amount of time required after the threshold reaches 2/3 V_{CC} to turn the output low. To explain further, Q_1 at the threshold input turns on after reaching 2/3 V_{CC}, which then turns on Q_5, which turns on Q_6. Current from Q_6 turns on Q_{16} which turns Q_{17} off. This allows current from Q_{19} to turn on Q_{20} and Q_{24} to given an output low. These steps cause the 2 µs max. delay as stated in the data sheet.

Also, a delay comparable to the turn-off time is the trigger release time. When the trigger is low, Q_{10} is on and turns on Q_{11} which turns on Q_{15}. Q_{15} turns off Q_{16} and allows Q_{17} to turn on. This turns off current to Q_{20} and Q_{24}, which results in output high. When the trigger is released, Q_{10} and Q_{11} shut off, Q_{15} turns off, Q_{16} turns on and the circuit then follows the same path and time delay explained as “turn off time”. This trigger release time is very important in designing the trigger pulse width so as not to interfere with the output signal as explained previously.

SO8: plastic small outline package; 8 leads; body width 3.9 mm SOT96-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

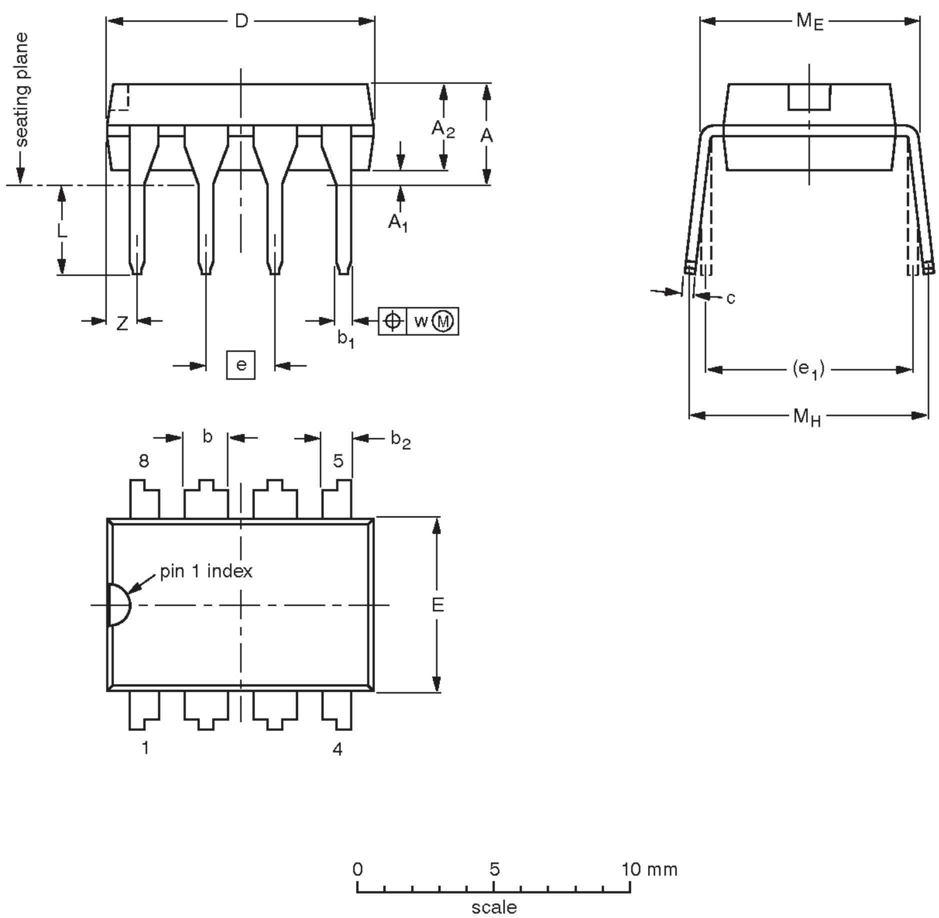
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT96-1	076E03	MS-012				~~97-05-22~~ 99-12-27

DIP8: plastic dual in-line package; 8 leads (300 mil) SOT97-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	b_2	c	D [(1)]	E [(1)]	e	e_1	L	M_E	M_H	w	Z [(1)] max.
mm	4.2	0.51	3.2	1.73 1.14	0.53 0.38	1.07 0.89	0.36 0.23	9.8 9.2	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	1.15
inches	0.17	0.020	0.13	0.068 0.045	0.021 0.015	0.042 0.035	0.014 0.009	0.39 0.36	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.045

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT97-1	050G01	MO-001	SC-504-8			~~95-02-04~~ 99-12-27

REVISION HISTORY

Rev	Date	Description
_2	20030214	**Product data (9397 750 11129); ECN 853-0036 29156 of 06 November 2002. Supersedes Product specification dated August 31, 1994.** Modifications: ● Remove all cerdip information from the data sheet. Package type discontinued. ● 'Absolute maximum ratings' table: T_{SOLD} rating changed from '+300 °C' to '+230 °C'.
	19940831	**Product specification; ECN 853-0036 13721 of 31 August 1994.** (Filename = NE_SA555X.pdf)

Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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